

AMENDMENT TO THE CLAIMS

1. (Currently Amended) In a A method for manufacturing an ink jet recording head provided with a pressure generating chamber, wherein the pressure generating chamber is constructed of a first plate, a second plate and a third plate, wherein the first plate is provided with a through-hole and sandwiched between the second plate and the third plate, the method comprising: ~~a step of forming said through-hole in said first plate, the improvement which comprises, in said step, the sub-steps of:~~

forming a first resist film and a second resist film on a first surface and a second surface of said first plate, respectively, wherein said first resist film and said second resist film assume substantially a same shape, but are different in length from each other when measured in a direction parallel to a flow direction of ink; and

forming said through-hole in said first plate by etching both said first surface and said second surface of said first plate with the use of said first resist film and said second resist film both of which serve as masks in said etching processing of said first plate.

2. (Currently Amended) The method for manufacturing the ink jet recording head ~~provided with the pressure generating chamber~~ according to claim 1, wherein: a thickness of said first plate is approximately 140 μm ; and

wherein a difference in length between said first resist film and said second resist film is within a range of from approximately 80 μm to approximately 140 μm .

3. (Currently Amended) In a A method for manufacturing an ink jet recording head provided with a pressure generating chamber, wherein the pressure generating chamber is constructed of a first plate, a second plate and a third plate, wherein the first plate is provided

with a through-hole and sandwiched between the second plate and the third plate, wherein one of said second plate and said third plate is provided with an ink outlet passage in its an ink discharge side, the method comprising: ~~a step of forming said ink outlet passage in said an ink discharge side of said one of said second plate and said third plate,~~ the improvement which comprises, in said step, the sub-steps of:

forming a first resist film and a second resist film on a first surface and a second surface of one of said first second plate and said third plate, respectively, wherein said first resist film and said second resist film assume substantially a same shape, but are offset from each other in a direction parallel to a flow direction of ink; and

forming said ~~through-hole in said first plate~~ ink outlet passage of one of said second plate and said third plate by etching both said first surface and said second surface of one of said first second plate and said third plate with the use of said first resist film and said second resist film both of which serve as masks in said etching processing of one of said first second plate and said third plate.

4. (Currently Amended) The method for manufacturing the ink jet recording head ~~provided with the pressure generating chamber~~ according to claim 3, wherein: a thickness of one of said first second plate and said third plate is approximately 140 μm ; and

wherein said first resist film and said second resist film are offset from each other by a value ranging from approximately 40 μm to approximately 70 μm .

5-6. (Canceled)

7. (New) The method according to claim 1, wherein said first plate comprises a pair of sides with substantially smooth surfaces.
8. (New) The method according to claim 1, wherein said first plate is comprised of at least one of a metal and a metal alloy.
9. (New) The method according to claim 1, further comprising:
 subjecting said first resist film and said second resist film to photo-exposure through a first mask and a second mask,
 wherein said first mask is slightly smaller than said second mask.
10. (New) The method according to claim 7, wherein said first mask comprises an elongated shape with a longitudinal axis extending in a direction parallel to said flow direction of said ink.
11. (New) The method according to claim 1, wherein said through-hole comprises an upper hole portion with an upstream side and a lower hole portion with an upstream side, said upstream side of said upper hole portion being displaced sidewardly in a direction parallel to said flow direction of said ink by a displacement amount relative to a corresponding said upstream side of said lower hole portion.
12. (New) The method according to claim 9, wherein said upper hole portion and said lower hole portion are each reduced in width near an ink inlet passage.

13. (New) The method according to claim 3, wherein said ink outlet passage comprises a first passage portion and a second passage portion each having a substantially semispherical shape.
14. (New) The method according to claim 3, wherein a center of said first surface is displaced in a side direction by a displacement amount relative to a center of said second surface.
15. (New) The method according to claim 3, wherein said first resist film and said second resist film are formed through a half-etching process.